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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/660,092	2 09/10/2003 Kah-Ong Tan		59846 (71987)	5934
Mr. Peter F. Co	7590 02/26/2007		EXAM	INER
EDWARDS & ANGELL, LLP			LAM, HUNG H	
101 Federal Street Boston, MA 02110			ART UNIT	PAPER NUMBER
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SHORTENED STATUTOR	Y PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE	
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Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

	Application No.	Applicant(s)
	10/660,092	TAN ET AL.
Office Action Summary	Examiner	Art Unit
	Hung H. Lam	2622
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tin vill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).
Status		
Responsive to communication(s) filed on This action is FINAL. 2b)⊠ This Since this application is in condition for allowar closed in accordance with the practice under E	action is non-final. nce except for formal matters, pro	
Disposition of Claims		
4) ☐ Claim(s) 1-8 is/are pending in the application. 4a) Of the above claim(s) is/are withdray 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-8 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or		
9)⊠ The specification is objected to by the Examine 10)⊠ The drawing(s) filed on <u>09/10/03</u> is/are: a)⊠ a Applicant may not request that any objection to the c Replacement drawing sheet(s) including the correct 11)□ The oath or declaration is objected to by the Ex	ccepted or b) objected to by the drawing(s) be held in abeyance. See ion is required if the drawing(s) is ob	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119		
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the prior application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)).	ion No ed in this National Stage
Attachment(s)		
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal F 6) Other:	ate

DETAILED ACTION

Specification

1. The title of the invention is not descriptive. A new title is required that is clearly indicative of the invention to which the claims are directed.

Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 1, 4, 5 and 8 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tsuchiya (US-6,359,740) in view of Farrell (US-6,977,187).

With regarding claim 1, Tsuchiya a digital image capturing module assembly, which comprises:

a lens holder (Figs. 1, 3-6; 30, 20, 20a), which has one side defined as a focusing plane (20-20a), and which is formed with a plurality of aligning posts (pins 201;201a;301a;201c) on the periphery of the focusing plane (see Fig. 2-6) and is further formed with a ring plane

between the focusing plane and the aligning posts that completely surrounds the focusing plane (see ring surface 204 in Fig. 2; Col. 1, Ln. 65-Col. 2, Ln. 10); and

a photosensitive printed circuit board (10-10c), which is formed with a plurality of aligning holes (101a-101c) corresponding to the aligning posts on the lens holder (see Figs. 1 and 3-6), and which is mounted on the lens holder by fitting the aligning holes thereof to the aligning posts on the lens holder (see Figs. 1 and 3-6; Col. 1, Ln. 60-Col. 2, Ln. 67);

However, Tsuchiya fails to explicitly discloses an adhesive layer, which is coated over the periphery of the focusing plane and over the ring plane; and wherein the respective tips of the aligning posts on the lens holder are each melted into a bolting structure to secure the photosensitive printed circuit board firmly in position on the lens holder; and wherein the firmly-secured photosensitive printed circuit board forcefully presses against the adhesive layer to be thereby adhered firmly in position on the lens holder with the adhesive layer providing a sealed light-impenetrable effect at the junction between the photosensitive printed circuit board and the lens holder.

In the same field of endeavor, Farrell teaches a method for packaging an electronic and optoelectronic component (abstract; Col. 1; Ln. 14-16) wherein a bonding agent, an adhesive, and/or a susceptor (Clearweld) material (30) may be dispensed onto the distal end of each sidewall or onto the mating surface on the substrate, before lid assembly (Figs. 2-3; 10) is mated to populated substrate 20 (Figs. 2-3; 10; Col. 5, Ln. 8-14). Farrell further teaches that an Ultrasonic horn (Fig. 9; 40) can be used to melt the distal ends of the alignment pins to secure lid assembly 10 to substrate 20 (Col. 5, Ln. 14-23). In light of the teaching from Farrell, it would have been obvious to one of ordinary skill in the art at the time the invention was made

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to modify the device of Tsuchiya to apply bonding agent, an adhesive, and/or a susceptor (Clearweld 30) material onto the matting surface of a lens holder and melt the distal ends of the alignment pins in order to secure the lens holder and the circuit board/substrate. modifications thus not only prevent light from entering the junction between a circuit board and a lens holder, but also prevent dust and moisture from damaging the packaging device.

With regarding claim 4, Tsuchiya in view of Farrell discloses the digital image capturing module assembly wherein the aligning posts on the lens holder is made of plastics (Farrell: Col. 5, Ln. 8-23: it is inherent that the alignment pins 18 are made of plastics).

With regarding claim 5, the claim is a method claim of the apparatus claim 1. Therefore, claim 5 is analyzed and rejected as discussed in claim 1.

With regarding claim 8, the claim is a method claim of the apparatus claim 4. Therefore, claim 8 is analyzed and rejected as discussed in claim 4.

Claims 2, 3, 6 and 7 are rejected under 35 U.S.C. 103(a) as being unpatentable over 4. Tsuchiya in view of Farrell and further in view of Kim (US-2003/0,223,008).

With regarding claim 2, Tsuchiya in view of Farrell fails to explicitly disclose the digital image capturing module assembly, wherein the photosensitive printed circuit board is a CCDbased photosensitive printed circuit board.

In the same field of endeavor, Kim teaches an image sensor module having a CCD or CMOS image sensor as a basic component of the camera module ([0006]). Kim further teaches that a COB (chip on board) package can be used to reduce the height of the module ([0006]). In light of the teaching from Kim, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the device of Tsuchiya and Farrell by having a CCD or CMOS image sensor as a basic component of the camera module as taught by Kim. The modifications thus provide a flexible camera module, which can be used to mount CCD or CMOS imager.

With regarding **claim 3**, Tsuchiya in view of Farrell fails to explicitly disclose the digital image capturing module assembly, wherein the photosensitive printed circuit board is a CMOS-based photosensitive printed circuit board.

In the same field of endeavor, Kim teaches an image sensor module having a CCD or CMOS image sensor as a basic component of the camera module ([0006]). Kim further teaches that a COB (chip on board) package can be used to reduce the height of the module ([0006]). In light of the teaching from Kim, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify the device of Tsuchiya and Farrell by having a CCD or CMOS image sensor as a basic component of the camera module as taught by Kim. The modifications thus provide a flexible camera module, which can be used to mount CCD or CMOS imager.

With regarding **claim 6**, the claim is a method claim of the apparatus claim 2. Therefore, claim 6 is analyzed and rejected as discussed in claim 2.

With regarding **claim 7**, the claim is a method claim of the apparatus claim 3. Therefore, claim 7 is analyzed and rejected as discussed in claim 3.

Conclusion

- 5. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.
 - a) Ning (US-6,654,187) discloses a camera lens carrier for circuit board mounting.
 - b) Lung (US-6,977,783) discloses lens holder module, which can be clipped into a board.
 - c) Yamaguchi (US-7,092,174) discloses an image module wherein a board is mounted to the image module by a plurality of posts.
 - d) Tan (US-2004/0,227,848) discloses a camera module wherein the lens holder and the pc board are secured by adhesive.
 - d) Tan (US-2005/0,041,098) discloses a camera module wherein the lens holder and the pc board are secured by adhesive and melting pins.
- 6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hung H. Lam whose telephone number is 571-272-7367. The examiner can normally be reached on Monday Friday 8AM 5PM.

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, NGOC YEN VU can be reached on 571-272-7320. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

HL 02/07/07

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